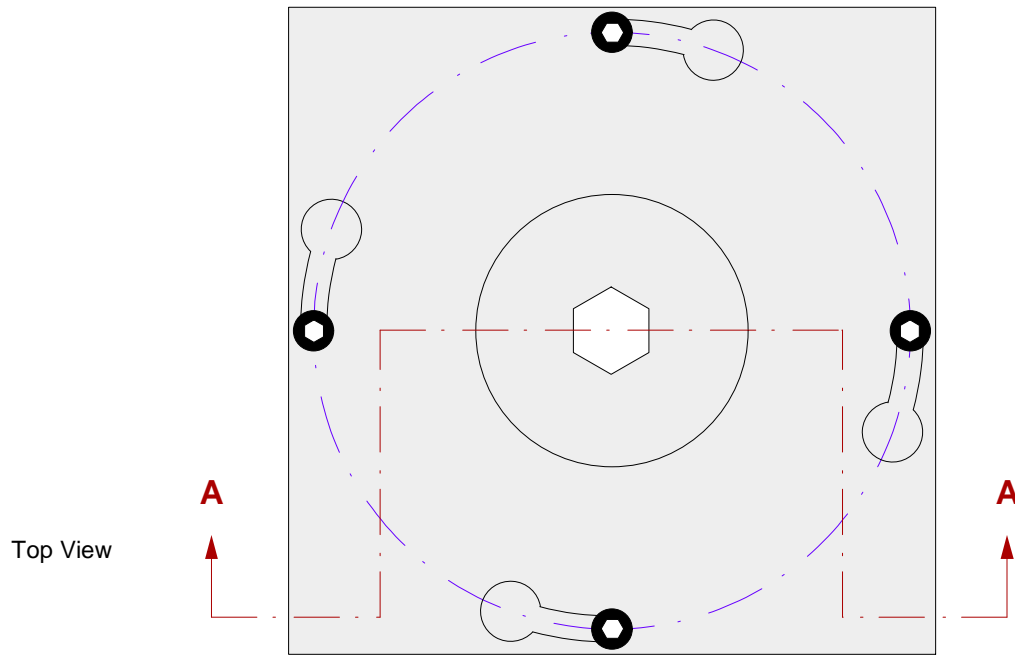


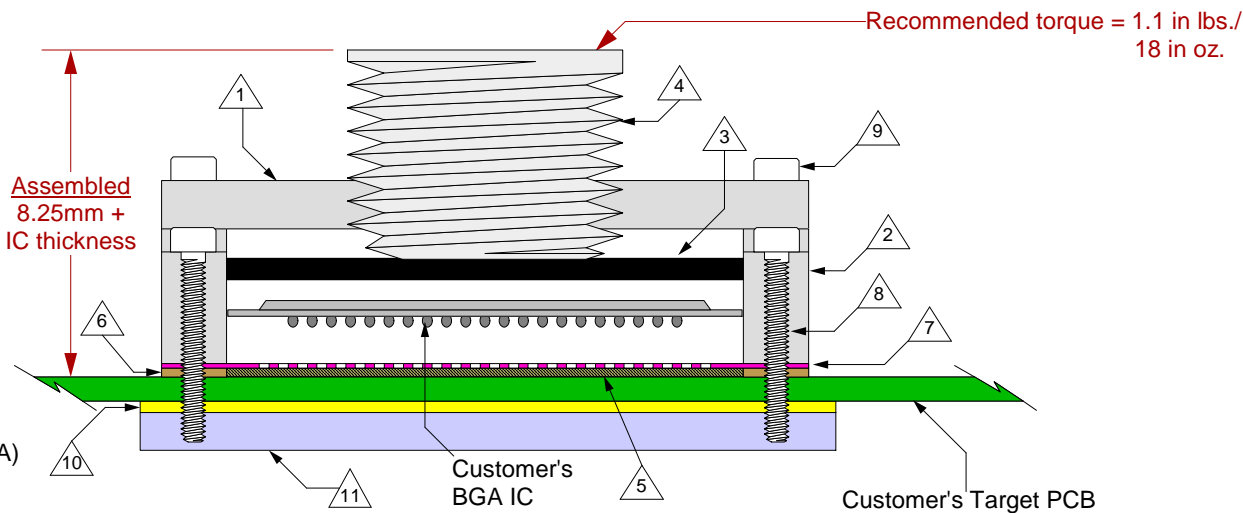
# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid




Top View

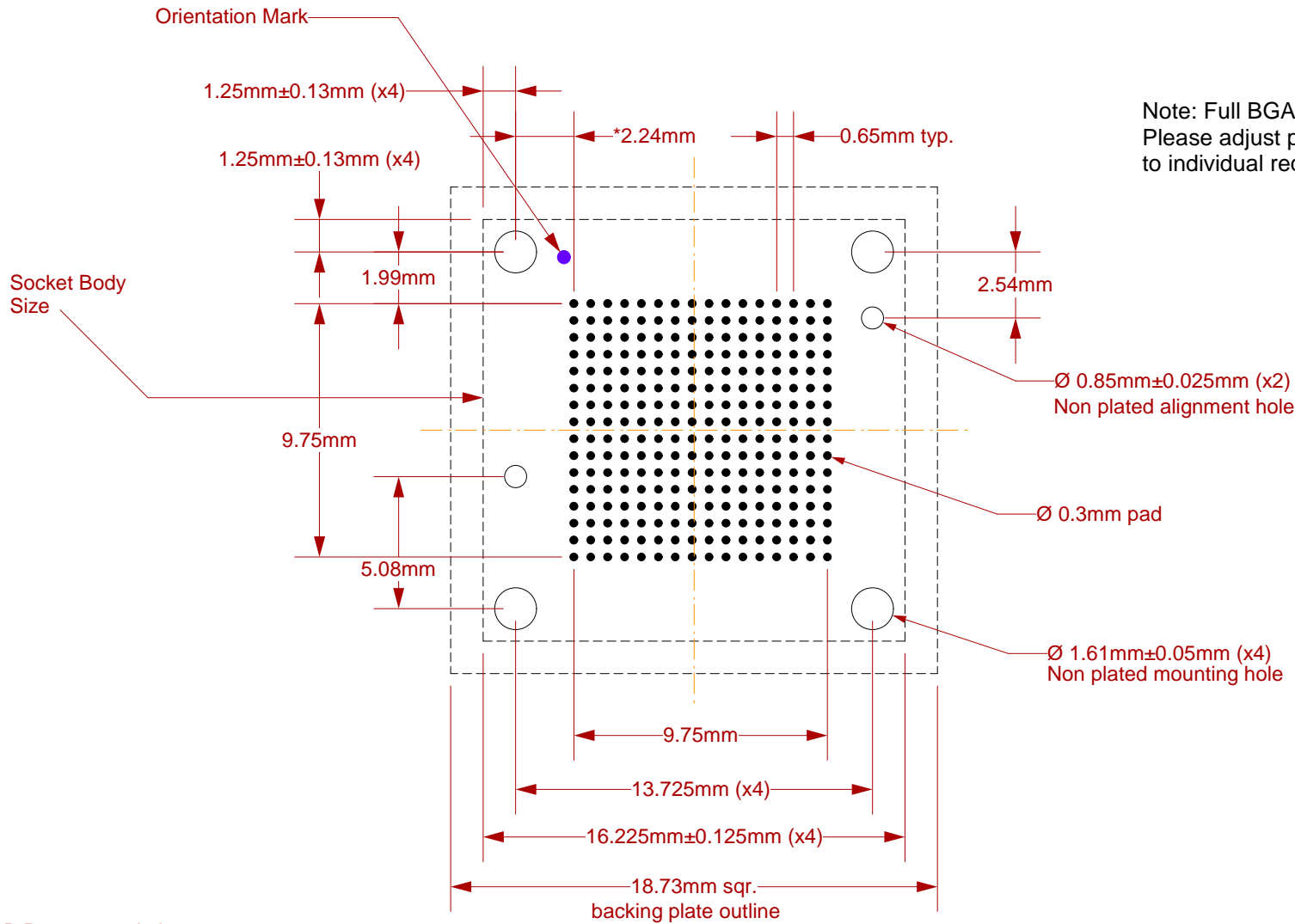


Side View  
(Section AA)

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

	<b>SG-BGA-7068 Drawing</b>	Status: Released	Scale: -	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 6/17/05
		File: SG-BGA-7068 Dwg	Modified: 7/7/09, AE	

All tolerances:  $\pm 0.125$ mm (unless stated otherwise). Materials and specifications are subject to change without notice.




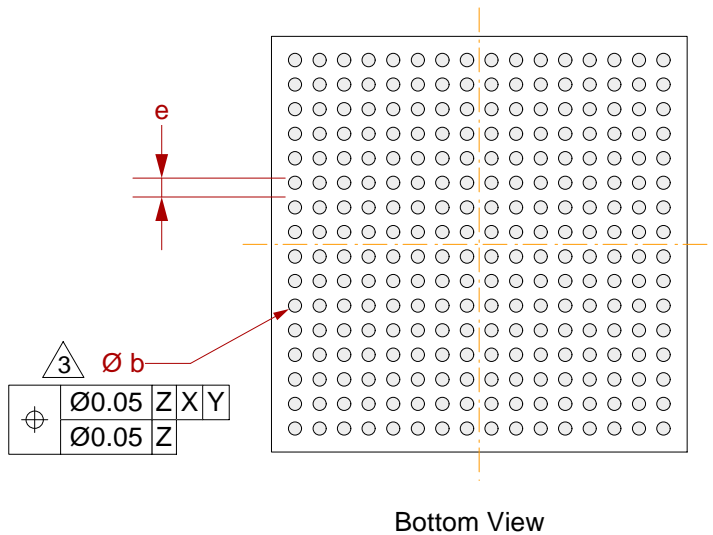
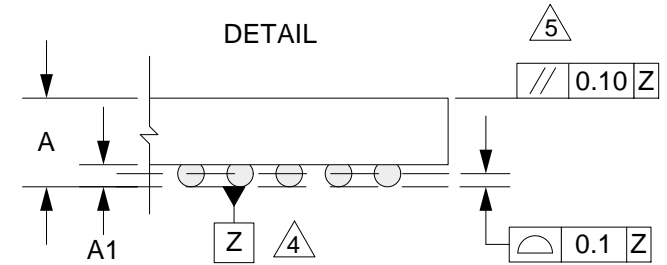
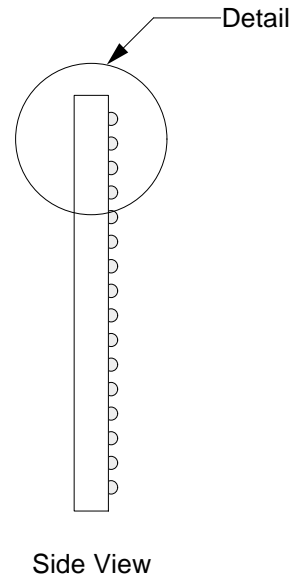
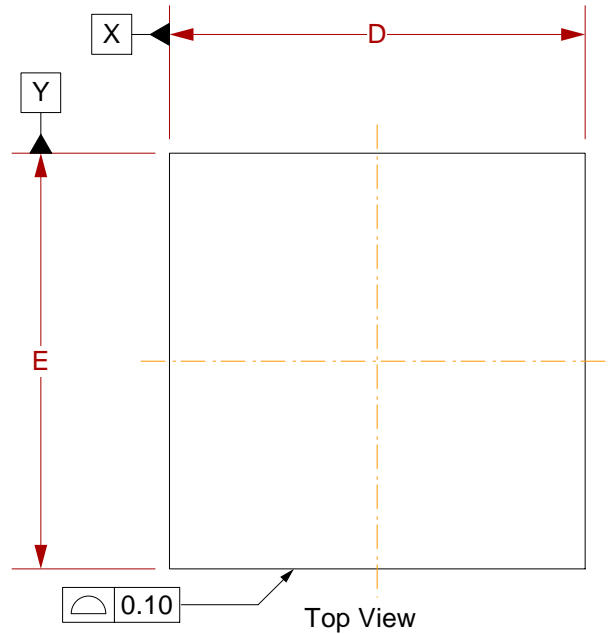
Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

Target PCB Recommendations

Total thickness: 1.6mm min.  
Plating: Gold or Solder finish  
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise  
Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.


	<b>SG-BGA-7068 Drawing</b>		Status: Released	Scale: 4:1	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: H. Hansen		Date: 6/17/05
			File: SG-BGA-7068 Dwg		Modified: 7/7/09, AE



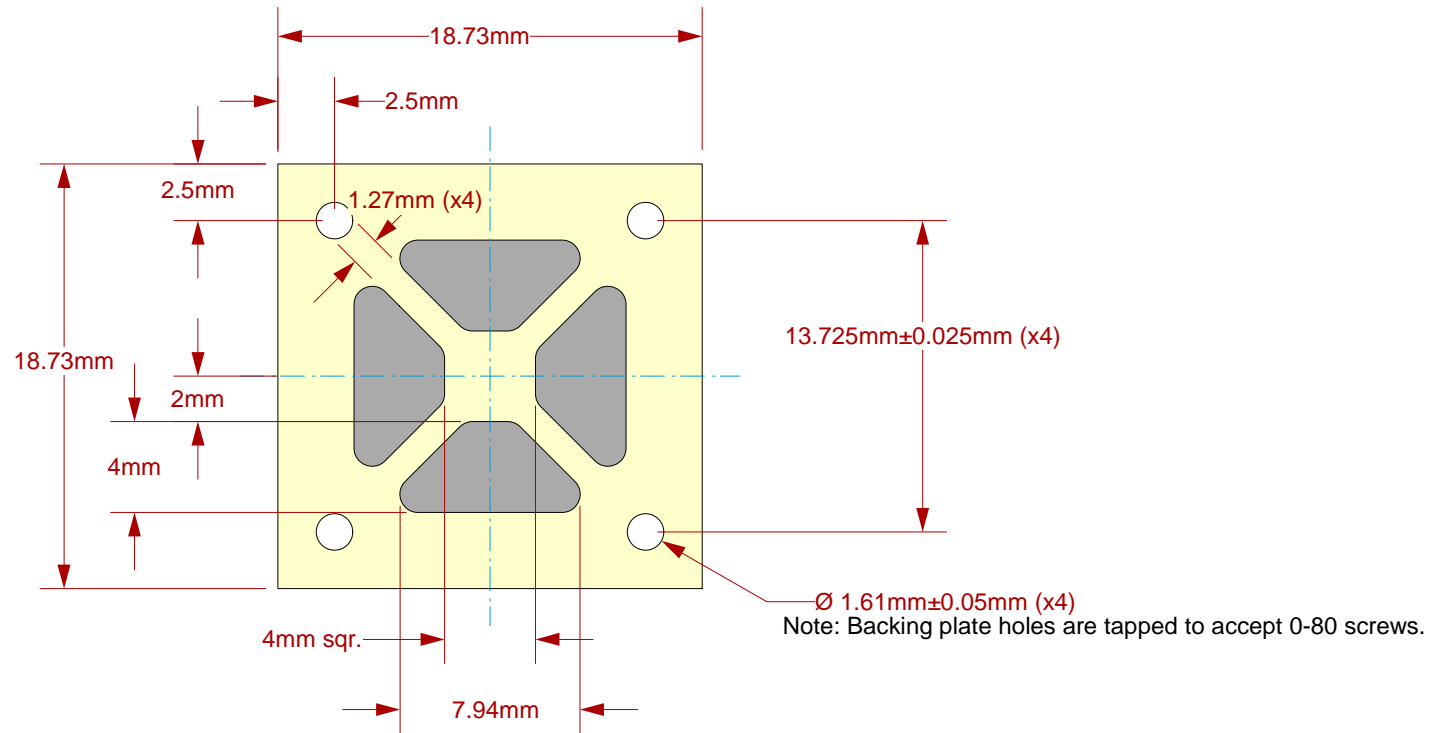
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.4
A1	0.25	0.35
b		0.35
D	11.0 BSC	
E	11.0 BSC	
e	0.65 BSC	

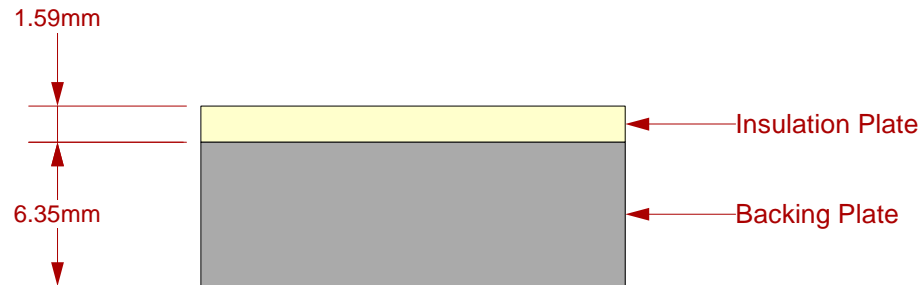
16 x 16 array

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	Drawing: H. Hansen		Date: 6/17/05	
	File: SG-BGA-7068 Dwg		Modified: 7/7/09, AE	

Top View




Side View



Description: Insulation Plate and Backing Plate

All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)

<b>SG-BGA-7068 Drawing</b>		Status: Released	Scale: 3:1	Rev: B
 © 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 6/17/05	
	File: SG-BGA-7068 Dwg		Modified: 7/7/09, AE	